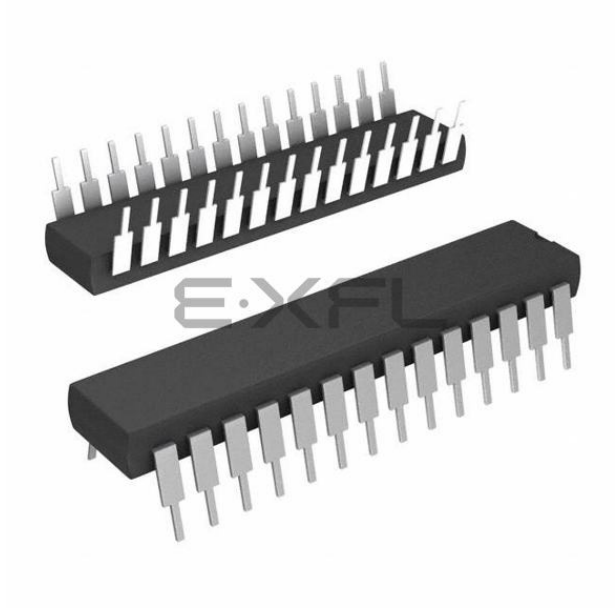

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Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	21
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep128gp502-i-sp

REGISTER 3-2: CORCON: CORE CONTROL REGISTER (CONTINUED)

bit 2 **SFA:** Stack Frame Active Status bit
- 1 = Stack frame is active; W14 and W15 address 0x0000 to 0xFFFF, regardless of DSRPAG and DSWPAG values
- 0 = Stack frame is not active; W14 and W15 address of EDS or Base Data Space

bit 1 **RND:** Rounding Mode Select bit(1)
- 1 = Biased (conventional) rounding is enabled
- 0 = Unbiased (convergent) rounding is enabled

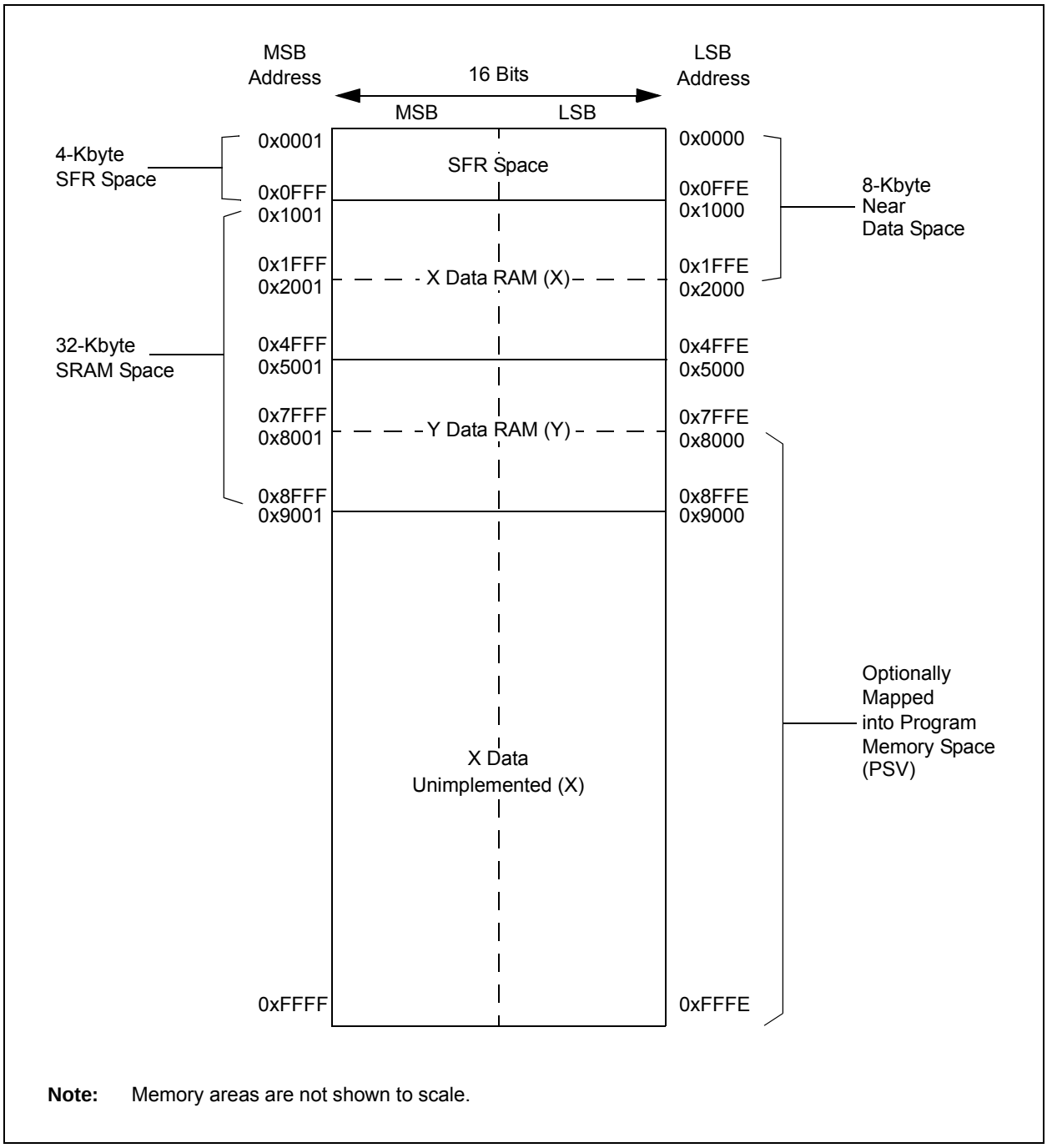
bit 0 **IF:** Integer or Fractional Multiplier Mode Select bit(1)
- 1 = Integer mode is enabled for DSP multiply
- 0 = Fractional mode is enabled for DSP multiply

Note 1: This bit is available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.

2: This bit is always read as '0'.

3: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

FIGURE 4-10: DATA MEMORY MAP FOR dsPIC33EP256MC20X/50X AND dsPIC33EP256GP50X DEVICES



Note: Memory areas are not shown to scale.

TABLE 4-11: PTG REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PTGCST	0AC0	PTGEN	—	PTGSIDL	PTGTOGL	—	PTGSWT	PTGSSEN	PTGIVIS	PTGSTRT	PTGWTO	—	—	—	—	PTGITM<1:0>		0000
PTGCON	0AC2	PTGCLK<2:0>			PTGDIV<4:0>					PTGPWD<3:0>				—	PTGWDT<2:0>			0000
PTGBTE	0AC4	ADCTS<4:1>				IC4TSS	IC3TSS	IC2TSS	IC1TSS	OC4CS	OC3CS	OC2CS	OC1CS	OC4TSS	OC3TSS	OC2TSS	OC1TSS	0000
PTGHOLD	0AC6	PTGHOLD<15:0>																0000
PTGT0LIM	0AC8	PTGT0LIM<15:0>																0000
PTGT1LIM	0ACA	PTGT1LIM<15:0>																0000
PTGSDLIM	0ACC	PTGSDLIM<15:0>																0000
PTGC0LIM	0ACE	PTGC0LIM<15:0>																0000
PTGC1LIM	0AD0	PTGC1LIM<15:0>																0000
PTGADJ	0AD2	PTGADJ<15:0>																0000
PTGL0	0AD4	PTGL0<15:0>																0000
PTGQPTR	0AD6	—	—	—	—	—	—	—	—	—	—	—	PTGQPTR<4:0>					0000
PTGQUE0	0AD8	STEP1<7:0>								STEP0<7:0>								0000
PTGQUE1	0ADA	STEP3<7:0>								STEP2<7:0>								0000
PTGQUE2	0ADC	STEP5<7:0>								STEP4<7:0>								0000
PTGQUE3	0ADE	STEP7<7:0>								STEP6<7:0>								0000
PTGQUE4	0AE0	STEP9<7:0>								STEP8<7:0>								0000
PTGQUE5	0AE2	STEP11<7:0>								STEP10<7:0>								0000
PTGQUE6	0AE4	STEP13<7:0>								STEP12<7:0>								0000
PTGQUE7	0AE6	STEP15<7:0>								STEP14<7:0>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

5.0 FLASH PROGRAM MEMORY

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Flash Programming"** (DS70609) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices contain internal Flash program memory for storing and executing application code. The memory is readable, writable and erasable during normal operation over the entire VDD range.

Flash memory can be programmed in two ways:

- In-Circuit Serial Programming™ (ICSP™) programming capability
- Run-Time Self-Programming (RTSP)

ICSP allows for a dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X device to be serially programmed while in the end application circuit. This is done with two lines for programming clock and programming data (one of the alternate programming pin pairs: PGECx/PGEDx), and three other lines for power (VDD), ground (VSS) and Master Clear (MCLR). This allows customers to manufacture boards with unprogrammed devices and then program the device just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

RTSP is accomplished using TBLRD (Table Read) and TBLWT (Table Write) instructions. With RTSP, the user application can write program memory data a single program memory word, and erase program memory in blocks or 'pages' of 1024 instructions (3072 bytes) at a time.

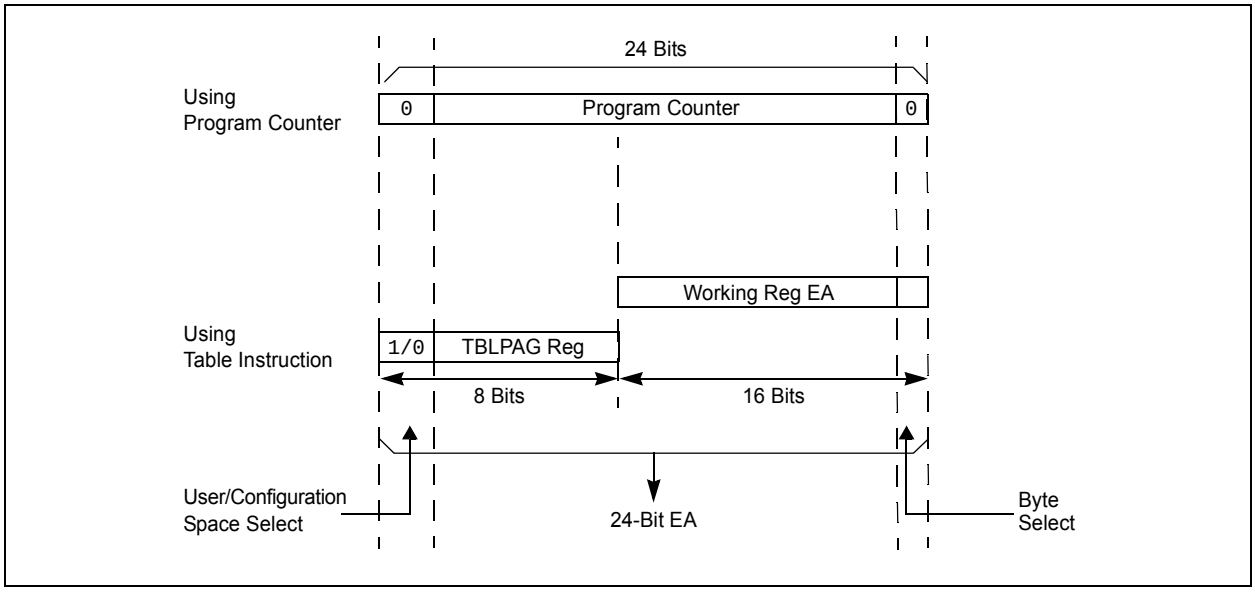
5.1 Table Instructions and Flash Programming

Regardless of the method used, all programming of Flash memory is done with the Table Read and Table Write instructions. These allow direct read and write access to the program memory space from the data memory while the device is in normal operating mode. The 24-bit target address in the program memory is formed using bits<7:0> of the TBLPAG register and the Effective Address (EA) from a W register, specified in the table instruction, as shown in Figure 5-1.

The TBLRDL and the TBLWTL instructions are used to read or write to bits<15:0> of program memory. TBLRDL and TBLWTL can access program memory in both Word and Byte modes.

The TBLRDH and TBLWTH instructions are used to read or write to bits<23:16> of program memory. TBLRDH and TBLWTH can also access program memory in Word or Byte mode.

FIGURE 5-1: ADDRESSING FOR TABLE REGISTERS



REGISTER 9-2: CLKDIV: CLOCK DIVISOR REGISTER (CONTINUED)

bit 4-0 **PLLPRE<4:0>:** PLL Phase Detector Input Divider Select bits (also denoted as 'N1', PLL prescaler)
11111 = Input divided by 33
•
•
•
00001 = Input divided by 3
00000 = Input divided by 2 (default)

Note 1: The DOZE<2:0> bits can only be written to when the DOZEN bit is clear. If DOZEN = 1, any writes to DOZE<2:0> are ignored.

2: This bit is cleared when the ROI bit is set and an interrupt occurs.

3: The DOZEN bit cannot be set if DOZE<2:0> = 000. If DOZE<2:0> = 000, any attempt by user software to set the DOZEN bit is ignored.

REGISTER 16-7: PWMCONx: PWMx CONTROL REGISTER

HS/HC-0	HS/HC-0	HS/HC-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
FLTSTAT(1)	CLSTAT(1)	TRGSTAT	FLTIEN	CLIEN	TRGIEN	ITB(2)	MDCS(2)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
DTC1	DTC0	DTCP(3)	—	MTBS	CAM(2,4)	XPRES(5)	IUE(2)
bit 7							bit 0

Legend:	HC = Hardware Clearable bit	HS = Hardware Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **FLTSTAT:** Fault Interrupt Status bit(1)
1 = Fault interrupt is pending
0 = No Fault interrupt is pending
This bit is cleared by setting FLTIEN = 0.

bit 14 **CLSTAT:** Current-Limit Interrupt Status bit(1)
1 = Current-limit interrupt is pending
0 = No current-limit interrupt is pending
This bit is cleared by setting CLIEN = 0.

bit 13 **TRGSTAT:** Trigger Interrupt Status bit
1 = Trigger interrupt is pending
0 = No trigger interrupt is pending
This bit is cleared by setting TRGIEN = 0.

bit 12 **FLTIEN:** Fault Interrupt Enable bit
1 = Fault interrupt is enabled
0 = Fault interrupt is disabled and the FLTSTAT bit is cleared

bit 11 **CLIEN:** Current-Limit Interrupt Enable bit
1 = Current-limit interrupt is enabled
0 = Current-limit interrupt is disabled and the CLSTAT bit is cleared

bit 10 **TRGIEN:** Trigger Interrupt Enable bit
1 = A trigger event generates an interrupt request
0 = Trigger event interrupts are disabled and the TRGSTAT bit is cleared

bit 9 **ITB:** Independent Time Base Mode bit(2)
1 = PHASEx register provides time base period for this PWM generator
0 = PTPER register provides timing for this PWM generator

bit 8 **MDCS:** Master Duty Cycle Register Select bit(2)
1 = MDC register provides duty cycle information for this PWM generator
0 = PDCx register provides duty cycle information for this PWM generator

Note 1: Software must clear the interrupt status here and in the corresponding IFSx bit in the interrupt controller.
2: These bits should not be changed after the PWMx is enabled (PTEN = 1).
3: DTC<1:0> = 11 for DTCP to be effective; otherwise, DTCP is ignored.
4: The Independent Time Base (ITB = 1) mode must be enabled to use Center-Aligned mode. If ITB = 0, the CAM bit is ignored.
5: To operate in External Period Reset mode, the ITB bit must be '1' and the CLMOD bit in the FCLCONx register must be '0'.

REGISTER 19-2: I2CxSTAT: I2Cx STATUS REGISTER (CONTINUED)

bit 3 **S:** Start bit
1 = Indicates that a Start (or Repeated Start) bit has been detected last
0 = Start bit was not detected last
Hardware is set or clear when a Start, Repeated Start or Stop is detected.

bit 2 **R_W:** Read/Write Information bit (when operating as I^2C slave)
1 = Read – Indicates data transfer is output from the slave
0 = Write – Indicates data transfer is input to the slave
Hardware is set or clear after reception of an I^2C device address byte.

bit 1 **RBF:** Receive Buffer Full Status bit
1 = Receive is complete, I2CxRCV is full
0 = Receive is not complete, I2CxRCV is empty
Hardware is set when I2CxRCV is written with a received byte. Hardware is clear when software reads I2CxRCV.

bit 0 **TBF:** Transmit Buffer Full Status bit
1 = Transmit in progress, I2CxTRN is full
0 = Transmit is complete, I2CxTRN is empty
Hardware is set when software writes to I2CxTRN. Hardware is clear at completion of a data transmission.

REGISTER 23-7: AD1CSSH: ADC1 INPUT SCAN SELECT REGISTER HIGH(1)

R/W-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
CSS31	CSS30	—	—	—	CSS26(2)	CSS25(2)	CSS24(2)
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CSS31:** ADC1 Input Scan Selection bit
1 = Selects CTMU capacitive and time measurement for input scan (Open)
0 = Skips CTMU capacitive and time measurement for input scan (Open)

bit 14 **CSS30:** ADC1 Input Scan Selection bit
1 = Selects CTMU on-chip temperature measurement for input scan (CTMU TEMP)
0 = Skips CTMU on-chip temperature measurement for input scan (CTMU TEMP)

bit 13-11 **Unimplemented:** Read as '0'

bit 10 **CSS26:** ADC1 Input Scan Selection bit(2)
1 = Selects OA3/AN6 for input scan
0 = Skips OA3/AN6 for input scan

bit 9 **CSS25:** ADC1 Input Scan Selection bit(2)
1 = Selects OA2/AN0 for input scan
0 = Skips OA2/AN0 for input scan

bit 8 **CSS24:** ADC1 Input Scan Selection bit(2)
1 = Selects OA1/AN3 for input scan
0 = Skips OA1/AN3 for input scan

bit 7-0 **Unimplemented:** Read as '0'

Note 1: All AD1CSSH bits can be selected by user software. However, inputs selected for scan, without a corresponding input on the device, convert VREFL.

2: The OAx input is used if the corresponding op amp is selected (OPMODE (CMxCON<10>) = 1); otherwise, the ANx input is used.

REGISTER 25-6: CMxFLTR: COMPARATOR x FILTER CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	CFSEL2	CFSEL1	CFSEL0	CFLTREN	CFDIV2	CFDIV1	CFDIV0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as '0'

bit 6-4 **CFSEL<2:0>:** Comparator Filter Input Clock Select bits
111 = T5CLK(1)
110 = T4CLK(2)
101 = T3CLK(1)
100 = T2CLK(2)
011 = Reserved
010 = SYNCO1(3)
001 = FOSC(4)
000 = FP(4)

bit 3 **CFLTREN:** Comparator Filter Enable bit
1 = Digital filter is enabled
0 = Digital filter is disabled

bit 2-0 **CFDIV<2:0>:** Comparator Filter Clock Divide Select bits
111 = Clock Divide 1:128
110 = Clock Divide 1:64
101 = Clock Divide 1:32
100 = Clock Divide 1:16
011 = Clock Divide 1:8
010 = Clock Divide 1:4
001 = Clock Divide 1:2
000 = Clock Divide 1:1

Note 1: See the Type C Timer Block Diagram (Figure 13-2).
2: See the Type B Timer Block Diagram (Figure 13-1).
3: See the High-Speed PWMx Module Register Interconnection Diagram (Figure 16-2).
4: See the Oscillator System Diagram (Figure 9-1).

28.0 INSTRUCTION SET SUMMARY

Note: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

The dsPIC33EP instruction set is almost identical to that of the dsPIC30F and dsPIC33F. The PIC24EP instruction set is almost identical to that of the PIC24F and PIC24H.

Most instructions are a single program memory word (24 bits). Only three instructions require two program memory locations.

Each single-word instruction is a 24-bit word, divided into an 8-bit opcode, which specifies the instruction type and one or more operands, which further specify the operation of the instruction.

The instruction set is highly orthogonal and is grouped into five basic categories:

- Word or byte-oriented operations
- Bit-oriented operations
- Literal operations
- DSP operations
- Control operations

Table 28-1 lists the general symbols used in describing the instructions.

The dsPIC33E instruction set summary in Table 28-2 lists all the instructions, along with the status flags affected by each instruction.

Most word or byte-oriented W register instructions (including barrel shift instructions) have three operands:

- The first source operand, which is typically a register 'Wb' without any address modifier
- The second source operand, which is typically a register 'Ws' with or without an address modifier
- The destination of the result, which is typically a register 'Wd' with or without an address modifier

However, word or byte-oriented file register instructions have two operands:

- The file register specified by the value 'f'
- The destination, which could be either the file register 'f' or the W0 register, which is denoted as 'WREG'

Most bit-oriented instructions (including simple rotate/shift instructions) have two operands:

- The W register (with or without an address modifier) or file register (specified by the value of 'Ws' or 'f')
- The bit in the W register or file register (specified by a literal value or indirectly by the contents of register 'Wb')

The literal instructions that involve data movement can use some of the following operands:

- A literal value to be loaded into a W register or file register (specified by 'k')
- The W register or file register where the literal value is to be loaded (specified by 'Wb' or 'f')

However, literal instructions that involve arithmetic or logical operations use some of the following operands:

- The first source operand, which is a register 'Wb' without any address modifier
- The second source operand, which is a literal value
- The destination of the result (only if not the same as the first source operand), which is typically a register 'Wd' with or without an address modifier

The MAC class of DSP instructions can use some of the following operands:

- The accumulator (A or B) to be used (required operand)
- The W registers to be used as the two operands
- The X and Y address space prefetch operations
- The X and Y address space prefetch destinations
- The accumulator write back destination

The other DSP instructions do not involve any multiplication and can include:

- The accumulator to be used (required)
- The source or destination operand (designated as Wso or Wdo, respectively) with or without an address modifier
- The amount of shift specified by a W register 'Wn' or a literal value

The control instructions can use some of the following operands:

- A program memory address
- The mode of the Table Read and Table Write instructions

TABLE 30-9: DC CHARACTERISTICS: WATCHDOG TIMER DELTA CURRENT (ΔI_{WDT})(1)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**	
DC61d	8	—	μA	-40°C	3.3V
DC61a	10	—	μA	+25°C	
DC61b	12	—	μA	+85°C	
DC61c	13	—	μA	+125°C	

Note 1: The ΔI_{WDT} current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current. All parameters are characterized but not tested during manufacturing.

TABLE 30-10: DC CHARACTERISTICS: DOZE CURRENT (I_{DOZE})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	**Typ.**	**Max.**	**Doze Ratio**	**Units**	**Conditions**		
Doze Current (I_{DOZE})(1)							
DC73a(2)	35	—	1:2	mA	-40°C	3.3V	FOSC = 140 MHz
DC73g	20	30	1:128	mA			
DC70a(2)	35	—	1:2	mA	+25°C	3.3V	FOSC = 140 MHz
DC70g	20	30	1:128	mA			
DC71a(2)	35	—	1:2	mA	+85°C	3.3V	FOSC = 140 MHz
DC71g	20	30	1:128	mA			
DC72a(2)	28	—	1:2	mA	+125°C	3.3V	FOSC = 120 MHz
DC72g	15	30	1:128	mA			

Note 1: I_{DOZE} is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all I_{DOZE} measurements are as follows:

- Oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (all PMDx bits are zeroed)
- CPU is executing `while(1)` statement
- JTAG is disabled

2: Parameter is characterized but not tested in manufacturing.

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
DI10		Any I/O Pin and $\overline{MCLR}$	VSS	—	0.2 VDD	V	
DI18		I/O Pins with SDAx, SCLx	VSS	—	0.3 VDD	V	SMBus disabled
DI19		I/O Pins with SDAx, SCLx	VSS	—	0.8	V	SMBus enabled
	VIH	**Input High Voltage**					
DI20		I/O Pins Not 5V Tolerant	0.8 VDD	—	VDD	V	**(Note 3)**
		I/O Pins 5V Tolerant and $\overline{MCLR}$	0.8 VDD	—	5.5	V	**(Note 3)**
		I/O Pins with SDAx, SCLx	0.8 VDD	—	5.5	V	SMBus disabled
		I/O Pins with SDAx, SCLx	2.1	—	5.5	V	SMBus enabled
	ICNPU	**Change Notification Pull-up Current**					
DI30			150	250	550	μA	VDD = 3.3V, VPIN = VSS
	ICNPD	**Change Notification Pull-Down Current(4)**					
DI31			20	50	100	μA	VDD = 3.3V, VPIN = VDD

Note 1: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: See the **"Pin Diagrams"** section for the 5V tolerant I/O pins.

4: VIL source < (VSS – 0.3). Characterized but not tested.

5: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

8: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
	IIL	**Input Leakage Current(1,2)**					
DI50		I/O Pins 5V Tolerant(3)	-1	—	+1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +85°C
DI51a		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +85°C
DI51b		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, -40°C ≤ TA ≤ +125°C
DI51c		I/O Pins Not 5V Tolerant(3)	-1	—	+1	μA	Analog pins shared with external reference pins, -40°C ≤ TA ≤ +125°C
DI55		$\overline{\text{MCLR}}$	-5	—	+5	μA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	-5	—	+5	μA	VSS ≤ VPIN ≤ VDD, XT and HS modes

Note 1: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: See the **"Pin Diagrams"** section for the 5V tolerant I/O pins.

4: VIL source < (VSS – 0.3). Characterized but not tested.

5: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

8: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

TABLE 30-59: ADC MODULE SPECIFICATIONS (10-BIT MODE)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)(1) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
ADC Accuracy (10-Bit Mode)							
AD20b	Nr	Resolution	10 Data Bits			bits	
AD21b	INL	Integral Nonlinearity	-0.625	—	0.625	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-1.5	—	1.5	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD22b	DNL	Differential Nonlinearity	-0.25	—	0.25	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-0.25	—	0.25	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD23b	GERR	Gain Error	-2.5	—	2.5	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-2.5	—	2.5	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD24b	EOFF	Offset Error	-1.25	—	1.25	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-1.25	—	1.25	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD25b	—	Monotonicity	—	—	—	—	Guaranteed
Dynamic Performance (10-Bit Mode)							
AD30b	THD	Total Harmonic Distortion(3)	—	64	—	dB	
AD31b	SINAD	Signal to Noise and Distortion(3)	—	57	—	dB	
AD32b	SFDR	Spurious Free Dynamic Range(3)	—	72	—	dB	
AD33b	FNYQ	Input Signal Bandwidth(3)	—	550	—	kHz	
AD34b	ENOB	Effective Number of Bits(3)	—	9.4	—	bits	

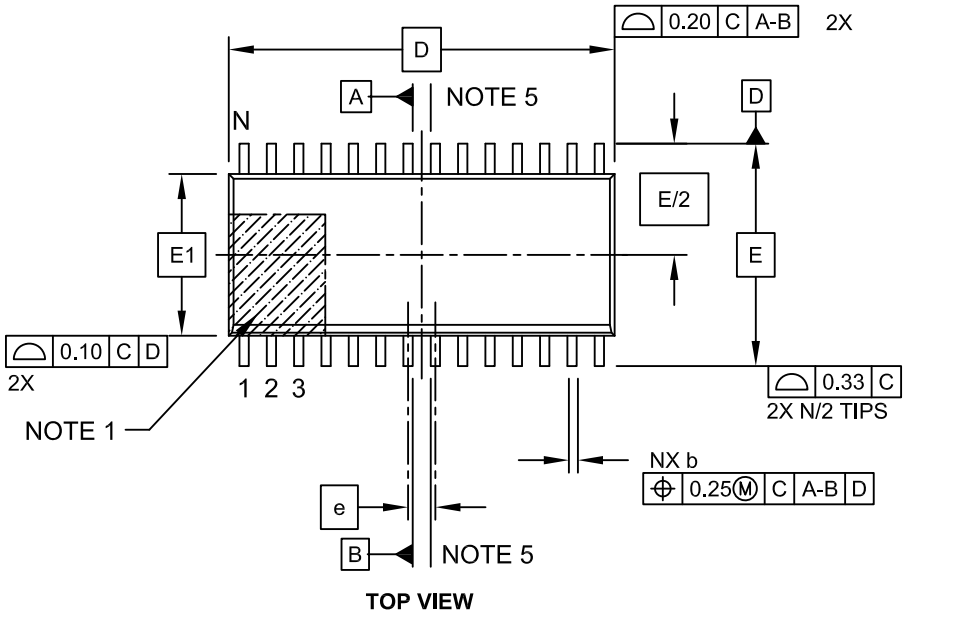
Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: For all accuracy specifications, VINL = AVSS = VREFL = 0V and AVDD = VREFH = 3.6V.

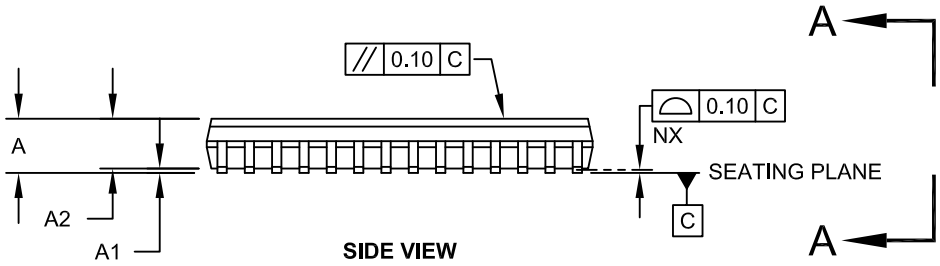
3: Parameters are characterized but not tested in manufacturing.

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

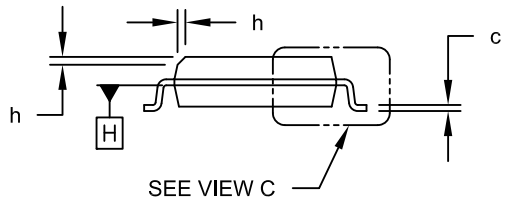
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW



VIEW A-A

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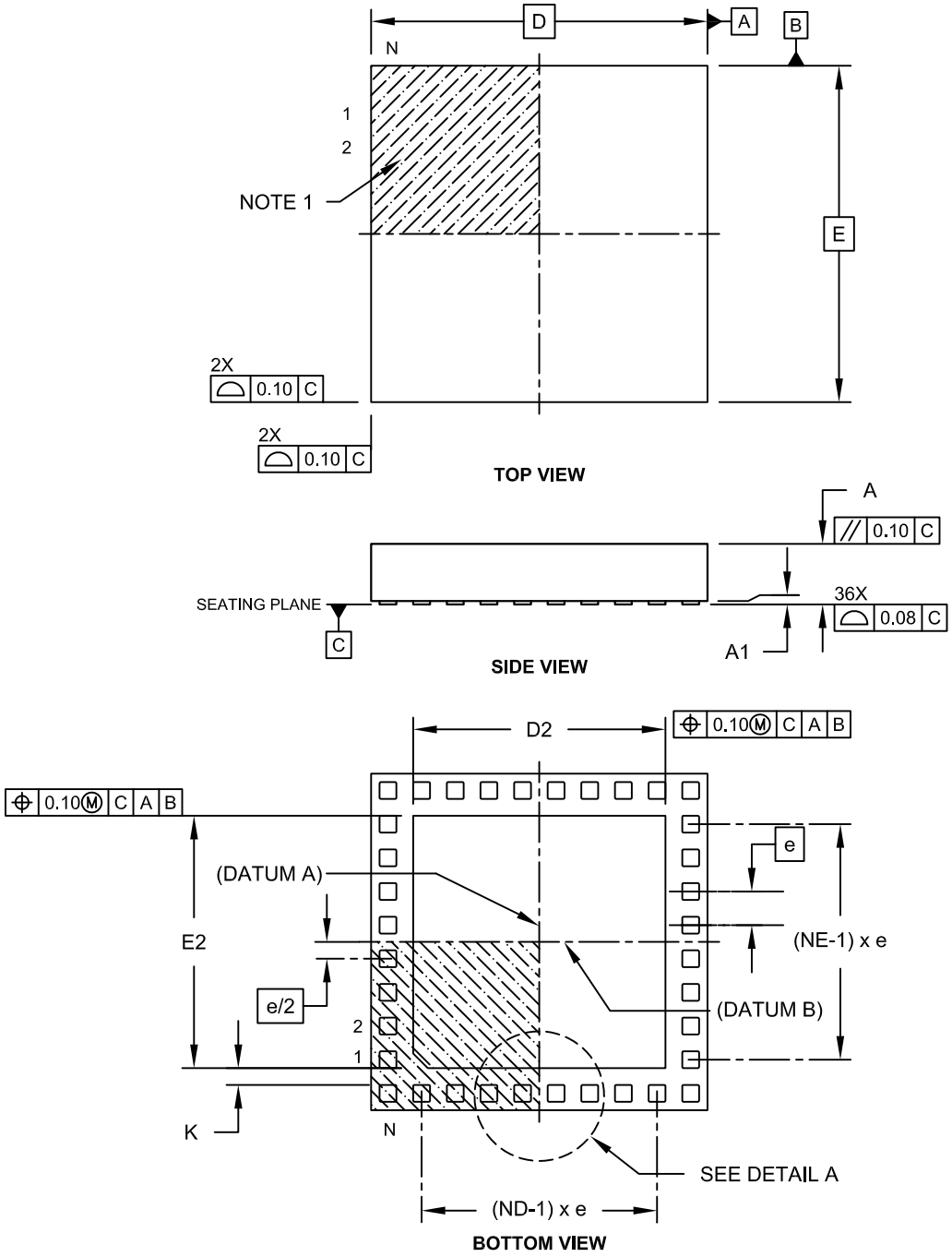
36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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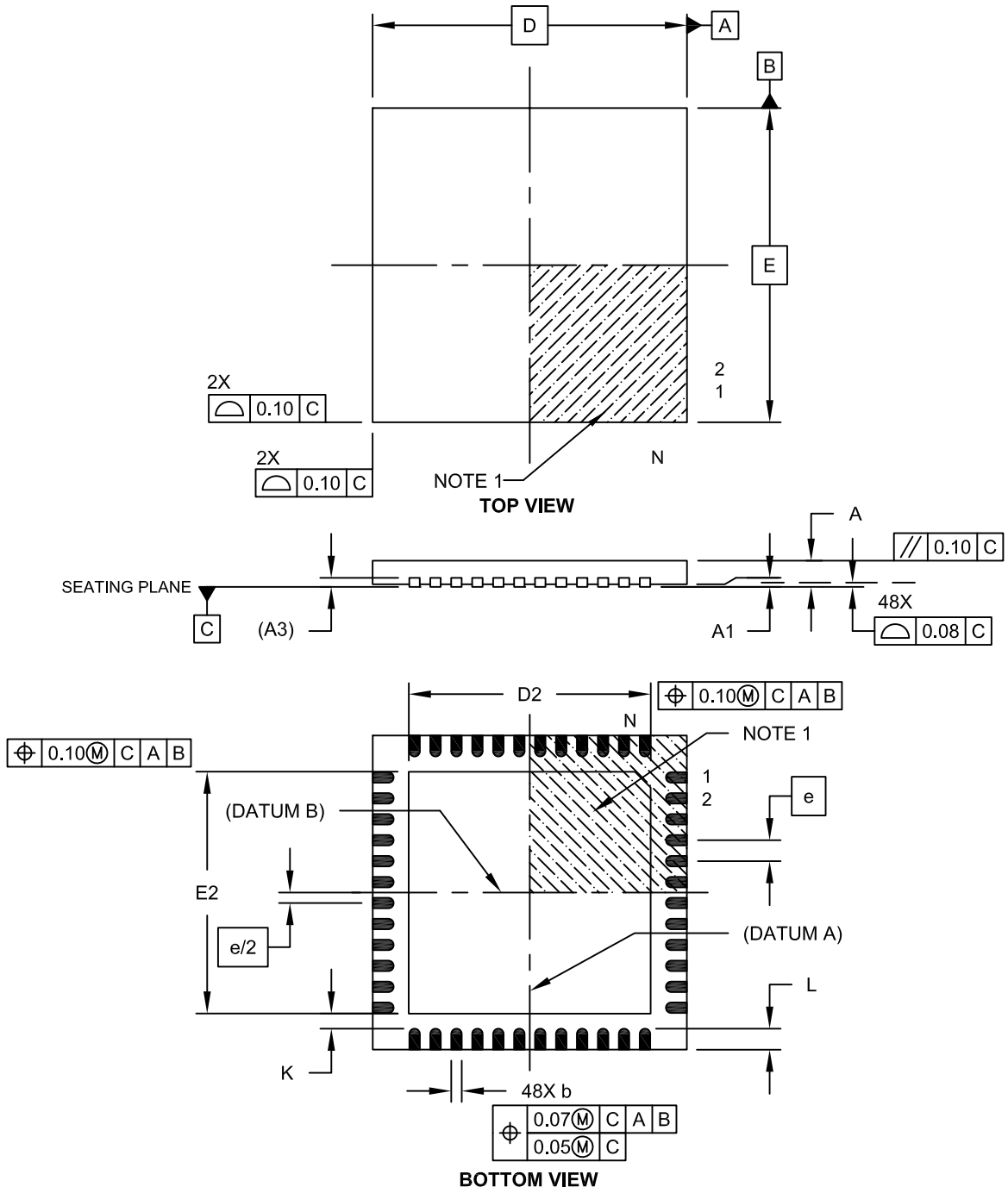
48-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 6x6x0.5 mm Body [UQFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-153A Sheet 1 of 2

APPENDIX A: REVISION HISTORY

Revision A (April 2011)

This is the initial released version of the document.

Revision B (July 2011)

This revision includes minor typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in Table A-1.

TABLE A-1: MAJOR SECTION UPDATES

Section Name	Update Description
"High-Performance, 16-bit Digital Signal Controllers and Microcontrollers"	Changed all pin diagrams references of VLAP to TLA.
Section 4.0 "Memory Organization"	Updated the All Resets values for CLKDIV and PLLFBD in the System Control Register Map (see Table 4-35).
Section 5.0 "Flash Program Memory"	Updated "one word" to "two words" in the first paragraph of **Section 5.2 "RTSP Operation"**.
Section 9.0 "Oscillator Configuration"	Updated the PLL Block Diagram (see Figure 9-2). Updated the Oscillator Mode, Fast RC Oscillator (FRC) with divide-by-N and PLL (FRCPLL), by changing (FRCDIVN + PLL) to (FRCPLL). Changed (FRCDIVN + PLL) to (FRCPLL) for COSC<2:0> = 001 and NOSC<2:0> = 001 in the Oscillator Control Register (see Register 9-1). Changed the POR value from 0 to 1 for the DOZE<1:0> bits, from 1 to 0 for the FRCDIV<0> bit, and from 0 to 1 for the PLLPOST<0> bit; Updated the default definitions for the DOZE<2:0> and FRCDIV<2:0> bits and updated all bit definitions for the PLLPOST<1:0> bits in the Clock Divisor Register (see Register 9-2). Changed the POR value from 0 to 1 for the PLLDIV<5:4> bits and updated the default definitions for all PLLDIV<8:0> bits in the PLL Feedback Division Register (see Register 9-2).
Section 22.0 "Charge Time Measurement Unit (CTMU)"	Updated the bit definitions for the IRNG<1:0> bits in the CTMU Current Control Register (see Register 22-3).
Section 25.0 "Op amp/ Comparator Module"	Updated the voltage reference block diagrams (see Figure 25-1 and Figure 25-2).

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 16.0 "High-Speed PWM Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)"	Updated the High-Speed PWM Module Register Interconnection Diagram (see Figure 16-2). Added the TRGCONx and TRIGx registers (see Register 16-12 and Register 16-14, respectively).
Section 21.0 "Enhanced CAN (ECAN™) Module (dsPIC33EPXXXGP/MC50X Devices Only)"	Updated the CANCKS bit value definitions in CiCTRL1: ECAN Control Register 1 (see Register 21-1).
Section 22.0 "Charge Time Measurement Unit (CTMU)"	Updated the IRNG<1:0> bit value definitions and added Note 2 in the CTMU Current Control Register (see Register 22-3).
Section 25.0 "Op amp/ Comparator Module"	Updated the Op amp/Comparator I/O Operating Modes Diagram (see Figure 25-1). Updated the User-programmable Blanking Function Block Diagram (see Figure 25-3). Updated the Digital Filter Interconnect Block Diagram (see Figure 25-4). Added **Section 25.1 "Op amp Application Considerations"**. Added Note 2 to the Comparator Control Register (see Register 25-2). Updated the bit definitions in the Comparator Mask Gating Control Register (see Register 25-5).
Section 27.0 "Special Features"	Updated the FICD Configuration Register, updated Note 1, and added Note 3 in the Configuration Byte Register Map (see Table 27-1). Added **Section 27.2 "User ID Words"**.
Section 30.0 "Electrical Characteristics"	Updated the following Absolute Maximum Ratings: • Maximum current out of V_{SS} pin • Maximum current into V_{DD} pin Added Note 1 to the Operating MIPS vs. Voltage (see Table 30-1). Updated all Idle Current (I_{IDLE}) Typical and Maximum DC Characteristics values (see Table 30-7). Updated all Doze Current (I_{DOZE}) Typical and Maximum DC Characteristics values (see Table 30-9). Added Note 2, removed Parameter CM24, updated the Typical values Parameters CM10, CM20, CM21, CM32, CM41, CM44, and CM45, and updated the Minimum values for CM40 and CM41, and the Maximum value for CM40 in the AC/DC Characteristics: Op amp/Comparator (see Table 30-14). Updated Note 2 and the Typical value for Parameter VR310 in the Op amp/ Comparator Reference Voltage Settling Time Specifications (see Table 30-15). Added Note 1, removed Parameter VRD312, and added Parameter VRD314 to the Op amp/Comparator Voltage Reference DC Specifications (see Table 30-16). Updated the Minimum, Typical, and Maximum values for Internal LPRC Accuracy (see Table 30-22). Updated the Minimum, Typical, and Maximum values for Parameter SY37 in the Reset, Watchdog Timer, Oscillator Start-up Timer, Power-up Timer Timing Requirements (see Table 30-24). The Maximum Data Rate values were updated for the SPI2 Maximum Data/Clock Rate Summary (see Table 30-35)

Revision F (November 2012)

Removed “Preliminary” from data sheet footer.

Revision G (March 2013)

This revision includes the following global changes:

- changes “$\overline{\text{FLTx}}$” pin function to “FLTx” on all occurrences
- adds **Section 31.0 “High-Temperature Electrical Characteristics”** for high-temperature (+150°C) data

This revision also includes minor typographical and formatting changes throughout the text.

Other major changes are referenced by their respective section in Table A-5.

TABLE A-5: MAJOR SECTION UPDATES

Section Name	Update Description
Cover Section	• Changes internal oscillator specification to 1.0% • Changes I/O sink/source values to 12 mA or 6 mA • Corrects 44-pin VTLA pin diagram (pin 32 now shows as 5V tolerant)
Section 4.0 “Memory Organization”	• Deletes references to Configuration Shadow registers • Corrects the spelling of the JTAGIP and PTGWDTIP bits throughout • Corrects the Reset value of all IOCON registers as C000h • Adds footnote to Table 4-42 to indicate the absence of Comparator 3 in 28-pin devices
Section 6.0 “Resets”	• Removes references to cold and warm Resets, and clarifies the initial configuration of the device clock source on all Resets
Section 7.0 “Interrupt Controller”	• Corrects the definition of GIE as “Global Interrupt Enable” (not “General”)
Section 9.0 “Oscillator Configuration”	• Clarifies the behavior of the CF bit when cleared in software • Removes POR behavior footnotes from all control registers • Corrects the tuning range of the TUN<5:0> bits in Register 9-4 to an overall range ±1.5%
Section 13.0 “Timer2/3 and Timer4/5”	• Clarifies the presence of the ADC Trigger in 16-bit Timer3 and Timer5, as well as the 32-bit timers
Section 15.0 “Output Compare”	• Corrects the first trigger source for SYNCSEL<4:0> (OCxCON2<4:0>) as OCxRS match
Section 16.0 “High-Speed PWM Module”	• Clarifies the source of the PWM interrupts in Figure 16-1 • Corrects the Reset states of IOCONx<15:14> in Register 16-13 as ‘11’
Section 17.0 “Quadrature Encoder Interface (QEI) Module”	• Clarifies the operation of the IMV<1:0> bits (QEICON<9:8>) with updated text and additional notes • Corrects the first prescaler value for QFVDIV<2:0> (QEI1OC<13:11>), now 1:128
Section 23.0 “10-Bit/12-Bit Analog-to-Digital Converter (ADC)”	• Adds note to Figure 23-1 that Op Amp 3 is not available in 28-pin devices • Changes “sample clock” to “sample trigger” in AD1CON1 (Register 23-1) • Clarifies footnotes on op amp usage in Registers 23-5 and 23-6
Section 25.0 “Op Amp/ Comparator Module”	• Adds Note text to indicate that Comparator 3 is unavailable in 28-pin devices • Splits Figure 25-1 into two figures for clearer presentation (Figure 25-1 for Op amp/ Comparators 1 through 3, Figure 25-2 for Comparator 4). Subsequent figures are renumbered accordingly. • Corrects reference description in xxxxx (now (AV_{DD} + AV_{SS})/2) • Changes CMSTAT<15> in Register 25-1 to “PSIDL”
Section 27.0 “Special Features”	• Corrects the addresses of all Configuration bytes for 512 Kbyte devices